



Material Content Data Sheet



Sales Product Name				IPP45N06S4L-08		Issued		24. January 2018	
MA#				MA001129854					
Package				PG-TO220-3-1		Weight*		2034.02 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	2.120	0.10	0.10	1042	1042	
leadframe	non noble metal	iron	7439-89-6	0.816	0.04		401		
	inorganic material	phosphorus	7723-14-0	0.245	0.01		120		
	non noble metal	copper	7440-50-8	815.335	40.09	40.14	400849	401370	
wire	non noble metal	aluminium	7429-90-5	2.756	0.14	0.14	1355	1355	
encapsulation	organic material	carbon black	1333-86-4	8.979	0.44		4415		
	plastics	epoxy resin	-	98.774	4.86		48561		
	inorganic material	silicondioxide	60676-86-0	490.879	24.13	29.43	241335	294311	
leadfinish	non noble metal	tin	7440-31-5	21.462	1.06	1.06	10552	10552	
plating	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		1		
solder	noble metal	silver	7440-22-4	0.054	0.00		27		
	non noble metal	tin	7440-31-5	0.043	0.00		21		
	non noble metal	lead	7439-92-1	2.074	0.10	0.10	1020	1068	
heatspreader	non noble metal	iron	7439-89-6	0.590	0.03		290		
	inorganic material	phosphorus	7723-14-0	0.177	0.01		87		
	non noble metal	copper	7440-50-8	589.466	28.98	29.02	289804	290181	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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